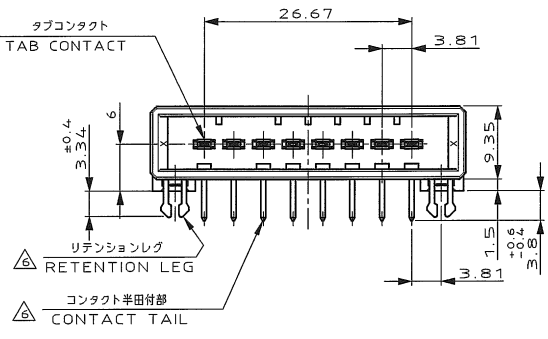
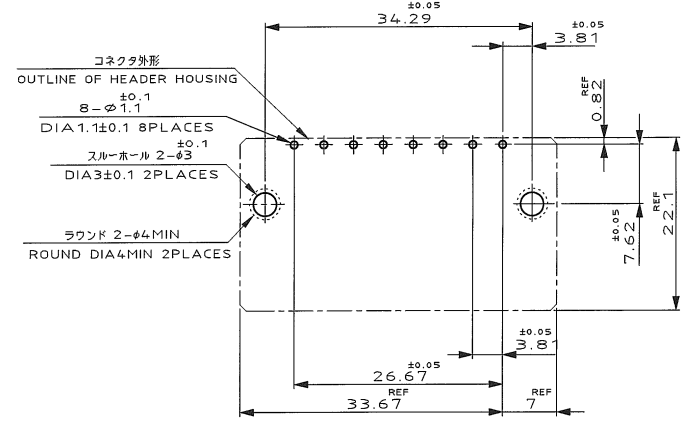
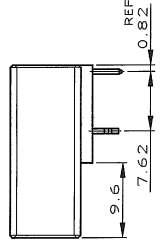
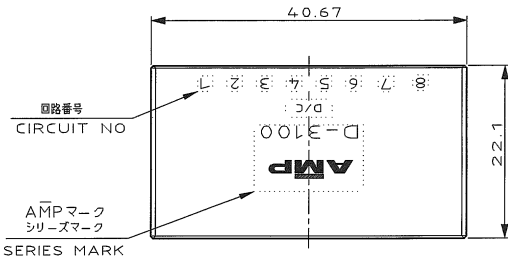


NUMBER 178297

3rd ANGLE PROJECTION

METRIC

PRINT DIST DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- 1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
- CONTACT: COPPER ALLOY
- RETENTION LEG: COPPER ALLOY
- △ FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER NI PLATING
- △ FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER NI PLATING
- △ FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- △ FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- △ FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
- コンタクト: 銅合金
- リテンションレグ: 銅合金
- △ めっき: コンタクト: 全面Ni下地 接触部: 0.38 μm MIN めっき
- △ めっき: コンタクト: 全面Ni下地 接触部: 0.76 μm MIN めっき
- △ めっき: コンタクト: 全面Ni下地 接触部: 2.0 μm MIN スズめっき
- △ めっき: リテンションレグとコンタクト半田付部
- △ めっき: リテンションレグとコンタクト半田付部
- △ めっき: リテンションレグとコンタクト半田付部

△	△	1-178297-5
△	△	1-178297-3
△	△	1-178297-2
(FINISH)		製品番号 (PART NO.)

B	REVISED (PJDO-0039-03)	T	SM	25 APR 91	DR.	N. Matsubara	DE.	14 JUN 91	DR.	N. Matsubara
A	REVISED (PJDO-0114-03)	T	SM	7-1 '91	DR.	N. Matsubara	DE.	14 JUN 91	DR.	N. Matsubara
O	PROPOSED	NM	SM	7-1 '91	DR.	N. Matsubara	DE.	14 JUN 91	DR.	N. Matsubara
LTR	REVISION RECORD	DR	CHK	DATE	CHK.	N. Matsubara	APP.	1 JUL 91	APP.	S. MAMBE

WIRE RANGE		INSULATION DIA		NAME	
mm (AWG)		mm (AWG)		8 POS SINGLE ROW	
				HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100	
MATERIAL		FINISH		GENERAL TOLERANCE	
SEE NOTE		SEE NOTE		100% ±0.3	
SEE NOTE		SEE NOTE		100% ±0.4	
SEE NOTE		SEE NOTE		100% ±0.5	
SEE NOTE		SEE NOTE		100% ±0.5	

Tyco Electronics AMP K.K. Kawasaki, Japan		SIZE LOC NUMBER		C= 178297	
SCALE		REV.		SHEET	
2-1		B		1 OF 1	

(CUSTOMER DRAWING) 顧客用図面